

May 2009

FDS4141_F085

P-Channel PowerTrench $^{\circledR}$ MOSFET -40V, -10.8A, 19.0m Ω

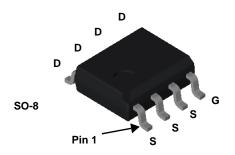
Features

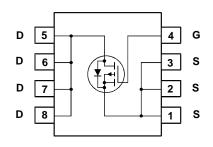
- Typ $r_{DS(on)} = 10.5 m\Omega$ at $V_{GS} = -10 V$, $I_D = -10.5 A$
- Typ $r_{DS(on)} = 14.8 \text{m}\Omega$ at $V_{GS} = -4.5 \text{V}$, $I_D = -8.4 \text{A}$
- Typ $Q_{q(TOT)} = 35nC$ at $V_{GS} = -10V$
- \blacksquare High performance trench technology for extremely low $r_{\mathsf{DS}(\mathsf{on})}$
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Control switch in synchronous & non-synchronous buck
- Load switch
- Inverter







MOSFET Maximum Ratings $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DSS}	Drain to Source Voltage	-40	V	
V_{GS}	Gate to Source Voltage	±20		
	Drain Current Continuous (V _{GS} = 10V)	-10.8	Α	
I D	Pulsed	-36	A	
E _{AS}	Single Pulse Avalanche Energy	229	mJ	
P_D	Power Dissipation	1.6	W	
T _J , T _{STG}	Operating and Storage Temperature	-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	30	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient SO-8, 1in ² copper pad area	81	°C/W

Package Marking and Ordering Information

I	Device Marking	Device	Package	Reel Size	Tape Width	Quantity
	FDS4141	FDS4141_F085	SO-8	13"	12mm	2500 units

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Parameter

Off Cha	Off Characteristics					
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -32V,	-	-	-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$,	-	-	±100	nA

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1.0	-1 7	-3.0	V
VGS(tn)	Cate to Course Threshold Voltage	00 00 0	1.0	10.5	13.0	•
		$I_D = -10.5A, V_{GS} = -10V$				
r _{DS(on)}	Diain to Source On Resistance	$I_D = -8.4A, V_{GS} = -4.5V$	-	14.8	19.0	mΩ
'DS(on)		$I_D = -10.5A$, $V_{GS} = -10V$, $T_J = 125^{\circ}C$	-	15.3	19.0	
9 _{FS}	Forward Transconductance	$I_D = -10.5A, V_{DD} = -5V$		34		S

Dynamic Characteristics

C _{iss}	Input Capacitance	.,		-	2005	-	pF
C _{oss}	Output Capacitance	V _{DS} = -20V, V _{GS} = —f = 1MHz	$V_{DS} = -20V, V_{GS} = 0V,$		355	-	pF
C _{rss}	Reverse Transfer Capacitance	-1 = 1WHZ		-	190	-	pF
R_g	Gate Resistance	f = 1MHz		-	5.0	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at -10V	$V_{GS} = 0 \text{ to } -10V$		-	35	45	nC
Q _{g(-5)}	Total Gate Charge at -5V	$V_{GS} = 0 \text{ to } -5V$	$V_{DD} = -20V$	-	18.6	24.2	nC
Q_{gs}	Gate to Source Gate Charge		$I_D = -10.5A$	-	5.2	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	6.6	-	nC

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Symbol Parameter		Test Conditions	Min	Тур	Max	Units	
Switchi	ing Characteristics						

t _{on}	Turn-On Time		-	-	25	ns
t _{d(on)}	Turn-On Delay Time		-	9.7	-	ns
t _r	Rise Time	$V_{DD} = -20V, I_{D} = -10.5A$ $V_{GS} = -10V, R_{GEN} = 6\Omega$	-	4.4	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -10V, R _{GEN} = 012	-	41	-	ns
t _f	Fall Time		-	11.6	-	ns
t _{off}	Turn-Off Time		-	-	84	ns

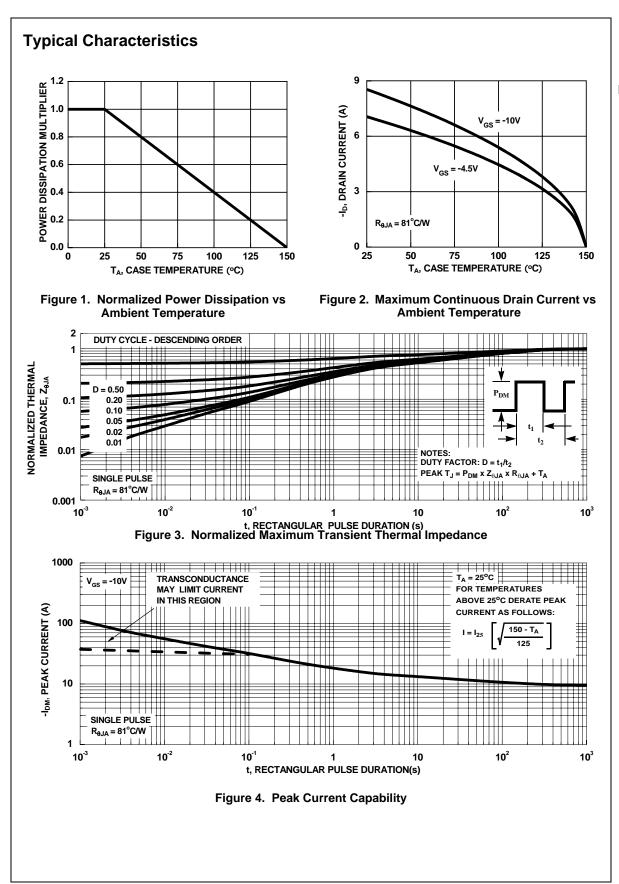
Drain-Source Diode Characteristics

V	Source to Drain Diode Voltage	I _{SD} = -10.5A	-	-0.8	-1.3	\/	
V_{SD}		I _{SD} = -2.1A		-0.7	-1.2	V	
t _{rr}	Reverse Recovery Time	L = 10.5A d /dt = 100A/va	-	26	34	ns	
Q _{rr}	Reverse Recovery Charge	I _F = -10.5A, d _{SD} /dt = 100A/μs	-	13.4	17.4	nC	

Notes

1: Starting $T_J = 25^{\circ}C$, L = 6.2mH, $I_{AS} = -8.6A$

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.



Typical Characteristics

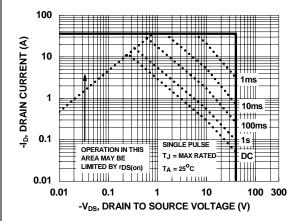
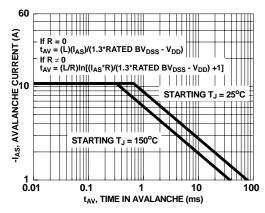


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

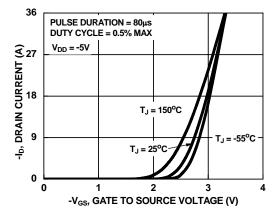


Figure 7. Transfer Characteristics

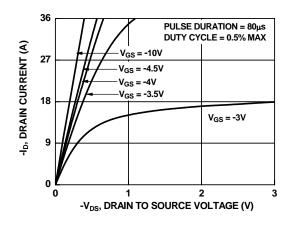


Figure 8. Saturation Characteristics

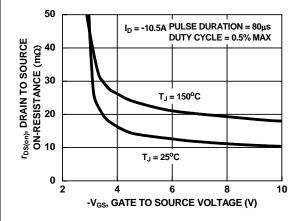


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

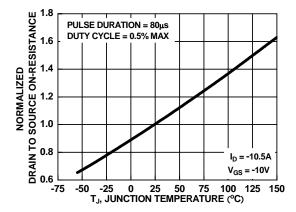


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

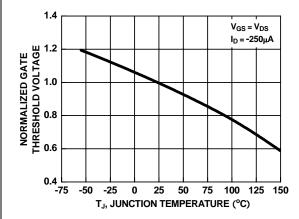


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

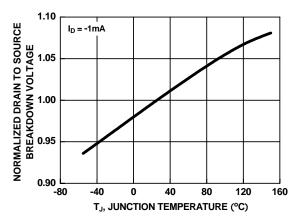


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

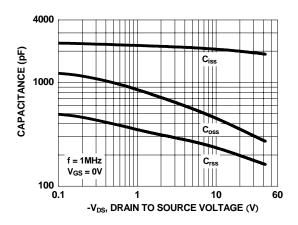


Figure 13. Capacitance vs Drain to Source Voltage

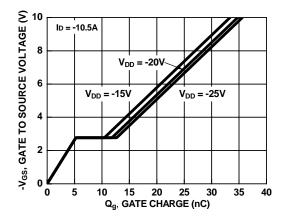


Figure 14. Gate Charge vs Gate to Source Voltage





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